

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A heat-sensitive lithographic printing plate precursor having on a support (1) an ink-receptive layer comprising an oleophilic organic high molecular compound, (2) a water-receptive layer easily allowing removal by a fountain solution or a printing ink when heated, which are arranged in this order and (3) an overcoat layer on the water-receptive layer wherein the overcoat layer contains a compound capable of converting light to heat; said water-receptive layer being a layer formed using a coating solution comprising a solvent capable of dissolving the organic high molecular compound of the ink-receptive layer in a proportion of 1 to 40 weight % of the total solvents in the coating solution.

2. (Original) The heat-sensitive lithographic printing plate precursor as in claim 1, wherein the water-receptive layer comprises a hydrophilic resin and a colloid of oxide or hydroxide of at least one element selected from the group consisting of beryllium, magnesium, aluminum, silicon, titanium, boron, germanium, tin, zirconium, iron, vanadium, antimony and transition metals.

3. (Original) The heat-sensitive lithographic printing plate precursor as in claim 2, wherein the hydrophilic resin is contained in a proportion of 0.1 to 30 weight % to the total solid components in the water-receptive layer.

4. (Original) The heat-sensitive lithographic printing plate precursor as in claim 2, wherein the hydrophilic resin is a hydroxyalkyl acrylate homopolymer, a hydroxyalkyl acrylate copolymer, a hydroxyalkyl methacrylate homopolymer or a hydroxyalkyl methacrylate copolymer.

5. (Original) The heat-sensitive lithographic printing plate precursor as in claim 1, wherein the water-receptive layer has a thickness of from 0.1 μm to 3 μm .

6. (Original) The heat-sensitive lithographic printing plate precursor as in claim 1, wherein the solvent capable of dissolving the organic high molecular component is selected from the group consisting of alcohols, ethers, ketones, esters, amides, γ -butyrolactone, methyl lactone and ethyl lactone.

7. (Previously Presented) The heat-sensitive lithographic printing plate precursor as in claim 1, wherein the water-receptive layer containing solution contains a mixture of solvents including alcohol as a main solvent and the solvent capable of dissolving the organic high molecular compound of the ink-receptive layer.

8. (Canceled)

9. (Previously Presented) The heat-sensitive lithographic printing plate precursor as in claim 1, wherein the overcoat layer is water-soluble overcoat layer which is removed upon printing.

10. (Canceled)

11. (Currently Amended) The heat-sensitive lithographic printing plate precursor as in claim 2, wherein ~~the hydrophilic resin contained in~~ the water-receptive layer does not contain a cross-linking agent and the hydrophilic resin is not cross-linked.

12. (New) A heat-sensitive lithographic printing plate precursor having on a support (1) an ink-receptive layer comprising an oleophilic organic high molecular compound, and (2) a water-receptive layer easily allowing removal by a fountain solution or a printing ink when heated wherein the water-receptive layer comprises a hydrophilic resin and a colloid of oxide or hydroxide of at least one element selected from the group consisting of beryllium, magnesium, aluminum, silicon, titanium, boron, germanium, tin, zirconium, iron, vanadium, antimony and transition metals, and wherein the water-receptive layer does not contain a cross-linking agent and the hydrophilic resin is not cross-linked, the ink-receptive layer and the water-receptive layer being arranged in this order: said water-receptive layer being a layer formed using a coating solution comprising a

solvent capable of dissolving the organic high molecular compound of the ink-receptive layer in a proportion of 1 to 40 weight % of the total solvents in the coating solution.

13. (New) The heat-sensitive lithographic printing plate precursor as in claim 12, wherein the hydrophilic resin is contained in a proportion of 0.1 to 30 weight % to the total solid components in the water-receptive layer.

14. (New) The heat-sensitive lithographic printing plate precursor as in claim 12, wherein the hydrophilic resin is a hydroxyalkyl acrylate homopolymer, a hydroxyalkyl acrylate copolymer, a hydroxyalkyl methacrylate homopolymer or a hydroxyalkyl methacrylate copolymer.

15. (New) The heat-sensitive lithographic printing plate precursor as in claim 12, wherein the water-receptive layer has a thickness of from 0.1 μm to 3 μm .

16. (New) The heat-sensitive lithographic printing plate precursor as in claim 12, wherein the solvent capable of dissolving the organic high molecular component is selected from the group consisting of alcohols, ethers, ketones, esters, amides, γ -butyrolactone, methyl lactone and ethyl lactone.

17. (New) The heat-sensitive lithographic printing plate precursor as in claim 12, wherein the water-receptive layer containing solution contains a mixture of solvents

including alcohol as a main solvent and the solvent capable of dissolving the organic high molecular compound of the ink-receptive layer.

18. (New) The heat-sensitive lithographic printing plate precursor as in claim 12, wherein the heat-sensitive lithographic printing plate precursor has an overcoat layer on the water-receptive layer.

19. (New) The heat-sensitive lithographic printing plate precursor as in claim 18, wherein the overcoat layer is water-soluble overcoat layer which is removed upon printing.

20. (New) The heat-sensitive lithographic printing plate precursor as in claim 18, wherein the overcoat layer contains a compound capable of converting light to heat.